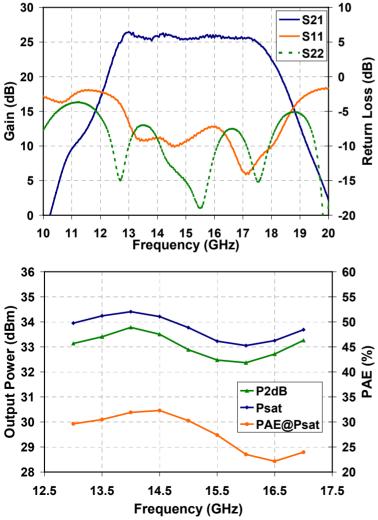


# 2 Watt Packaged Amplifier



Preliminary Measured Performance Bias Conditions:  $V_D = 7.5V$ ,  $I_D = 650mA$ 



# TGA2902-SCC-SG

### Key Features and Performance

- 34 dBm Midband Psat
- 26 dB Nominal Gain
- 8 dB Typical Return Loss
- 13 17 GHz Frequency Range
- Directional Power Detector with Reference
- 0.25µm pHEMT Technology
- Bias Conditions: 7.5V, 650mA
- Package Dimensions: 9.4 x 6.4 x 1.8 mm (370 x 250 x 71 mils)

### **Primary Applications**

- VSAT
- Point to Point

Note: Devices designated as EPU are typically early in their characterization process prior to finalizing all electrical and process specifications. Specifications are subject to change without notice.



### TGA2902-SCC-SG

#### TABLE I MAXIMUM RATINGS

Symbol	Parameter	Value	Notes
VD	Drain Voltage	8 V	<u>1/ 2</u> /
V <sub>G</sub>	Gate Voltage Range	-5V to 0V	<u>1</u> /
I <sub>D</sub>	Drain Supply Current (Quiescent)	1300 mA	<u>1/ 2</u> /
I <sub>G</sub>	Gate Supply Current	18 mA	<u>1</u> /
P <sub>IN</sub>	Input Continuous Wave Power	24 dBm	<u>1/ 2</u> /
PD	Power Dissipation	6.15 W	<u>1/ 2/ 3/</u>
T <sub>CH</sub>	Operating Channel Temperature	150 <sup>0</sup> C	<u>4</u> /
Τ <sub>M</sub>	Mounting Temperature (30 Seconds)	220 <sup>0</sup> C	
T <sub>STG</sub>	Storage Temperature	-65 to 150 <sup>0</sup> C	

- 1/ These ratings represent the maximum operable values for this device
- **2**/ Combinations of supply voltage, supply current, input power, and output power shall not exceed P<sub>D</sub> at a package base temperature of 70°C
- 3/ When operated at this bias condition with a baseplate temperature of 70°C, the MTTF is reduced from 4.8E+6 to 1.0E+6 hours
- <u>4</u>/ Junction operating temperature will directly affect the device median time to failure (MTTF). For maximum life, it is recommended that junction temperatures be maintained at the lowest possible levels.

Parameter	Test Conditions	Т <sub>сн</sub> (°С)	R <sub>⊛JC</sub> (°C/W)	MTTF (hrs)
R <sub>⊛JC</sub> Thermal Resistance (Channel to Backside of Package)	$V_{D}$ = 7.5V $I_{D}$ = 650mA $P_{DISS}$ = 4.88W $T_{BASE}$ = 70°C	132.3	12.8	4.8E+6

#### TABLE II THERMAL INFORMATION

Note: Devices designated as EPU are typically early in their characterization process prior to finalizing all electrical and process specifications. Specifications are subject to change without notice.



#### TABLE III TGA2902-1-SCC-SG RF CHARACTERIZATION TABLE $(T_A = 25^{\circ}C, Nominal)$ $(Vd = 7.5V, Id = 650mA \pm 5\%)$

Symbol	Parameter	Test Conditions	Limits			Units	Notes
			Min	Тур	Max		
Gain	Small Signal Gain	F = 13-17	22	26	29	dB	<u>1/ 2</u> /
IRL	Input Return Loss	F = 13-17		8		dB	
ORL	Output Return Loss	F = 13-17		8		dB	
PSAT	Output Power @ Pin = +14dBm	F = 13-17	32.5	33.5		dBm	1/
P2dB	Output Power @ 2dB Gain Compression	F = 13-17		32.5		dBm	
ID	Drain Current @ Pin = +14dBm	F = 13-17		1100	1300	mA	
l <sub>G</sub>	Gate Current @ Pin = +14dBm	F = 13-17		6	18	mA	
IP3	Third Order Intercept Point	F = 13-17		38		dBm	
PAE	Power Added Efficiency @ Pin -= +14dBm	F = 13-17		30		%	

Note: Table IV Lists the RF Characteristics of typical devices as determined by fixtured measurements.

- 1/ Data taken at 500MHz steps
- 2/ Maximum Pin = -10dBm

Note: Devices designated as EPU are typically early in their characterization process prior to finalizing all electrical and process specifications. Specifications are subject to change without notice.



#### TABLE IV TGA2902-2-SCC-SG RF CHARACTERIZATION TABLE $(T_A = 25^{\circ}C, Nominal)$ $(Vd = 7.5V, Id = 650mA \pm 5\%)$

Symbol	Parameter	Test Conditions	Limits		Units	Notes	
-			Min	Тур	Max		
Gain	Small Signal Gain	F = 13.75-14.5	23	26	29	dB	<u>1/ 2</u> /
IRL	Input Return Loss	F = 13.75-14.5		8		dB	
ORL	Output Return Loss	F = 13.75-14.5		8		dB	
PSAT	Output Power @ Pin = +14dBm	F = 13.75-14.5	33.5	34.0		dBm	<u>1</u> /
P2dB	Output Power @ 2dB Gain Compression	F = 13.75-14.5		33.5		dBm	
I <sub>D</sub>	Drain Current @ Pin = +14dBm	F = 13.75-14.5		1100	1300	mA	
I <sub>G</sub>	Gate Current @ Pin = +14dBm	F = 13.75-14.5		6	18	mA	
IP3	Third Order Intercept Point	F = 13.75-14.5		38.5		dBm	
PAE	Power Added Efficiency @ Pin -= +14dBm	F = 13.75-14.5		30		%	

Note: Table III Lists the RF Characteristics of typical devices as determined by fixtured measurements.

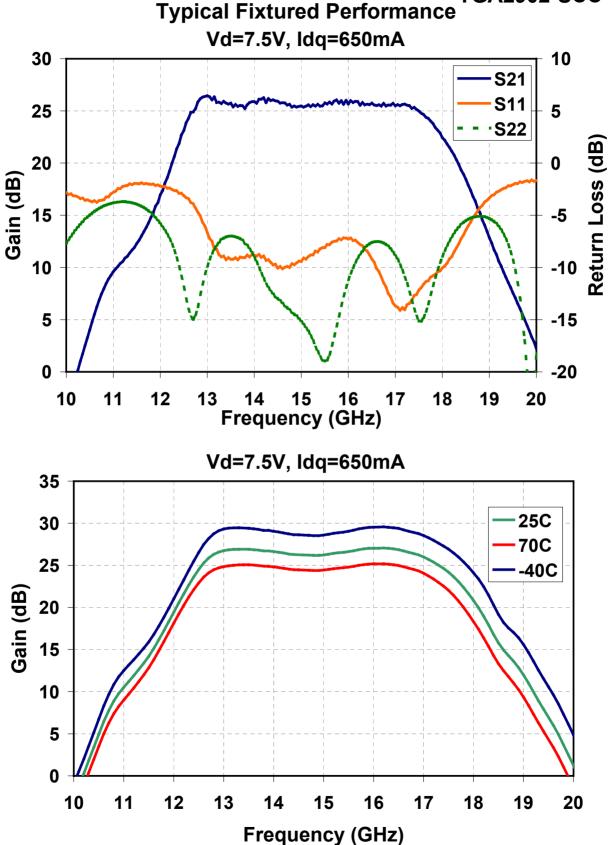
#### 1/ Data taken at 250MHz steps

2/ Maximum Pin = -10dBm

Note: Devices designated as EPU are typically early in their characterization process prior to finalizing all electrical and process specifications. Specifications are subject to change without notice.



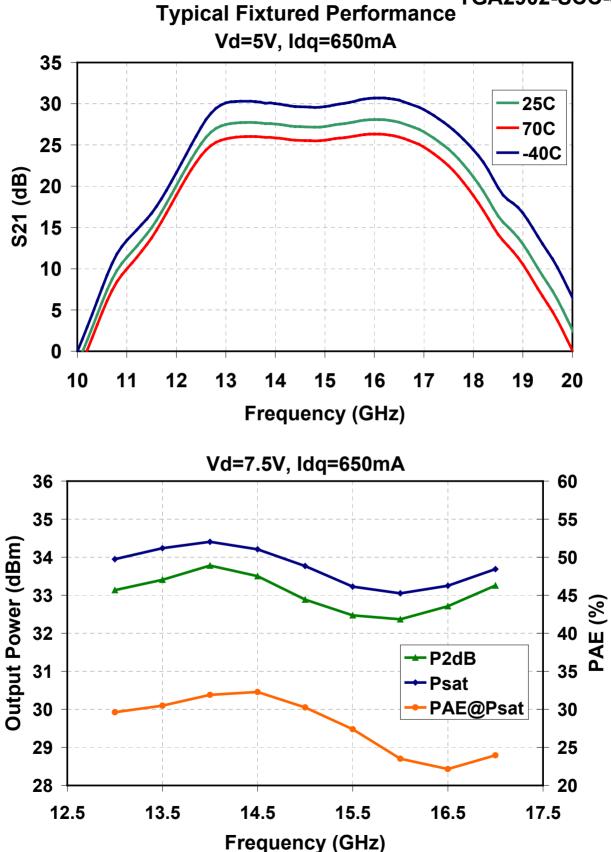
TGA2902-SCC-SG



Note: Devices designated as EPU are typically early in their characterization process prior to finalizing all electrical and process specifications. Specifications are subject to change without notice.



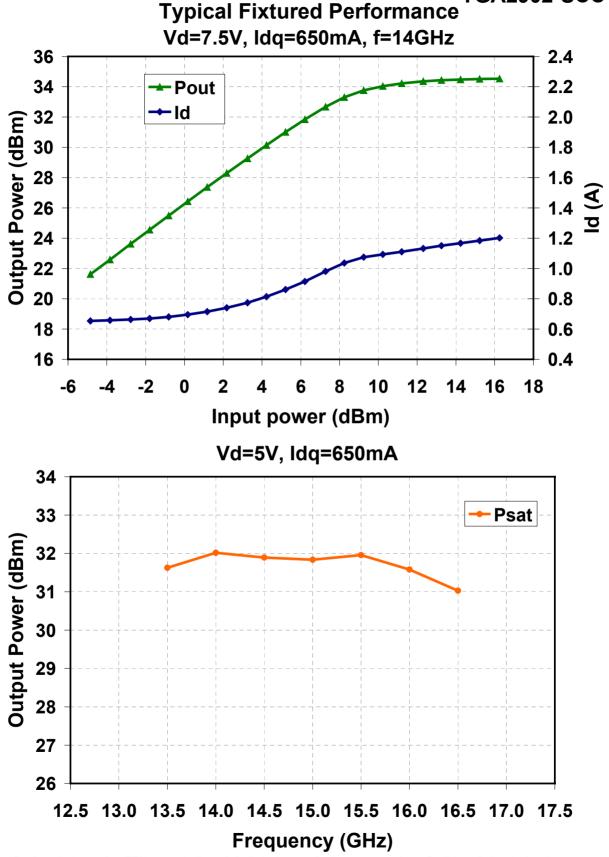
TGA2902-SCC-SG



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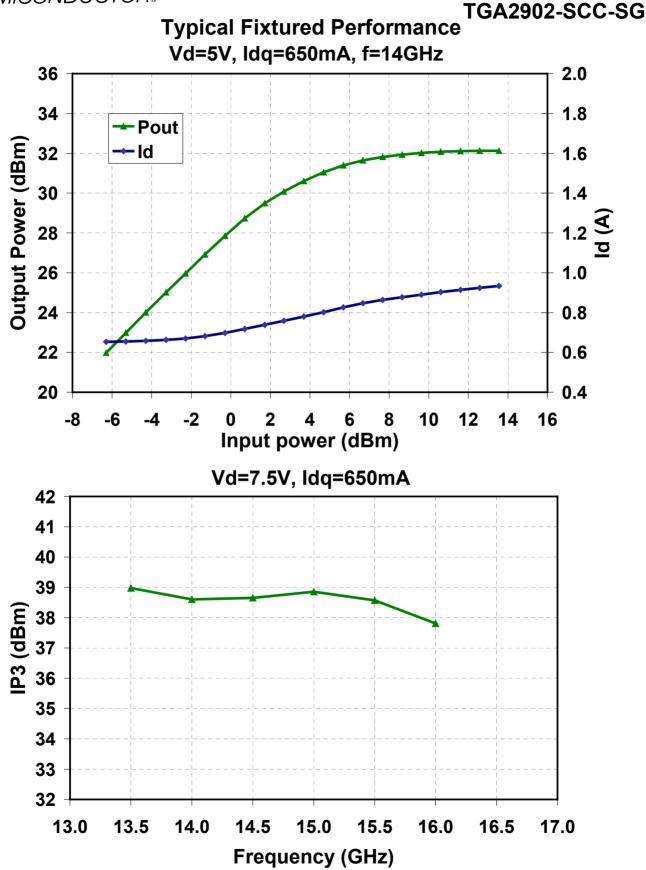


Note: Devices designated as EPU are typically early in their characterization process prior to finalizing all electrical and process specifications. Specifications are subject to change without notice.



Product Data Sheet

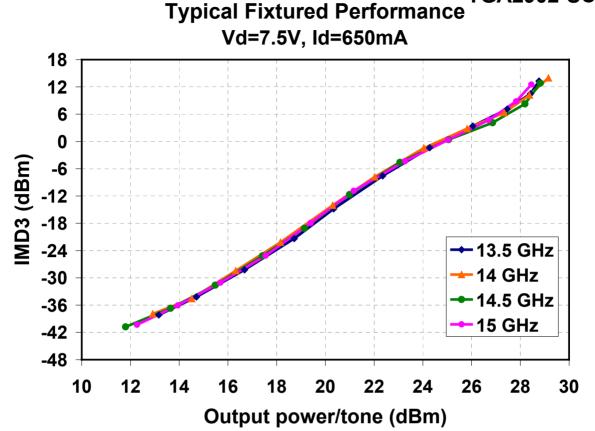
May 18, 2004



Note: Devices designated as EPU are typically early in their characterization process prior to finalizing all electrical and process specifications. Specifications are subject to change without notice.



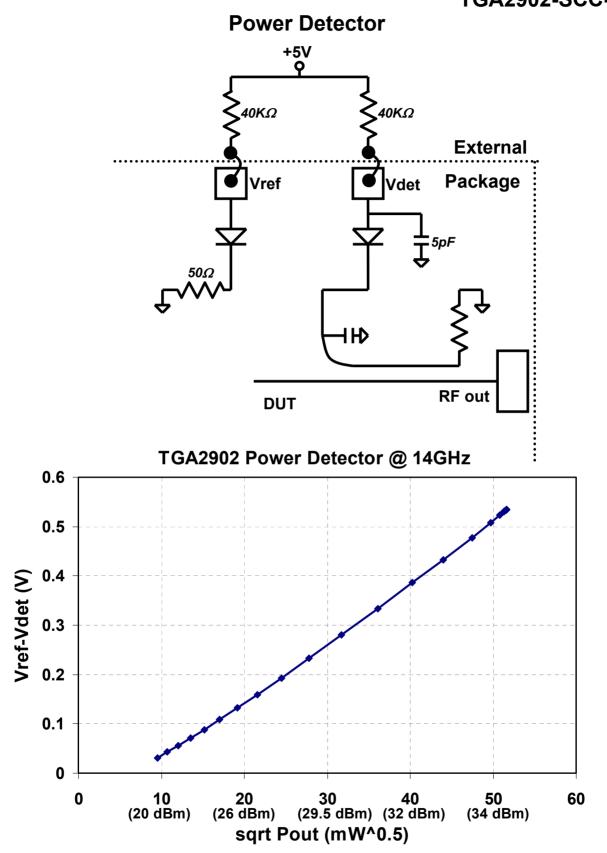
TGA2902-SCC-SG



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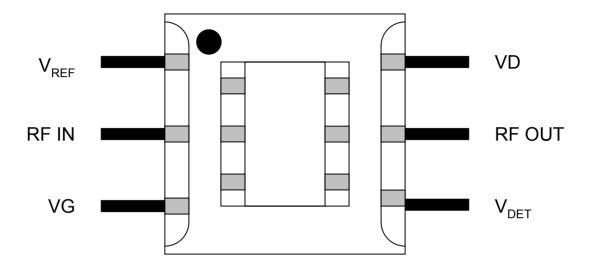
Product Data Sheet May 18, 2004 TGA2902-SCC-SG



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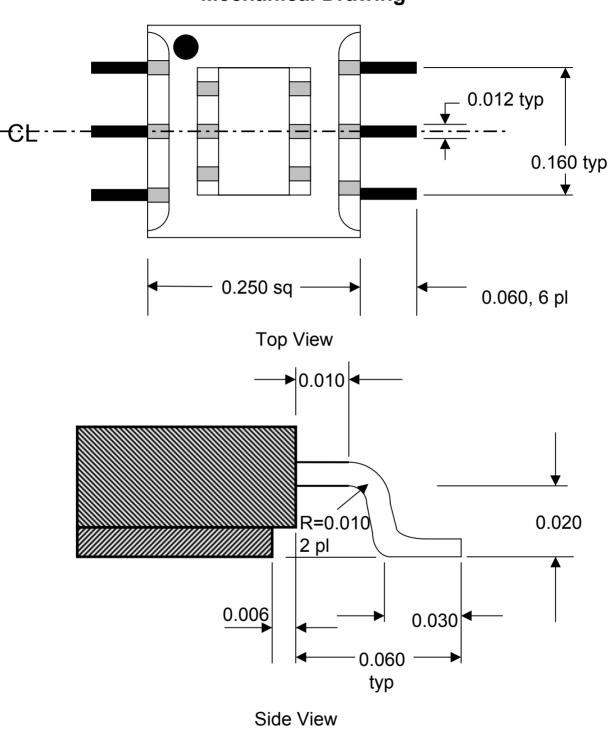
## Package Pinout Diagram



GaAs MMIC devices are susceptible to damage from Electrostatic Discharge. Proper precautions should be observed during handling, assembly and test.

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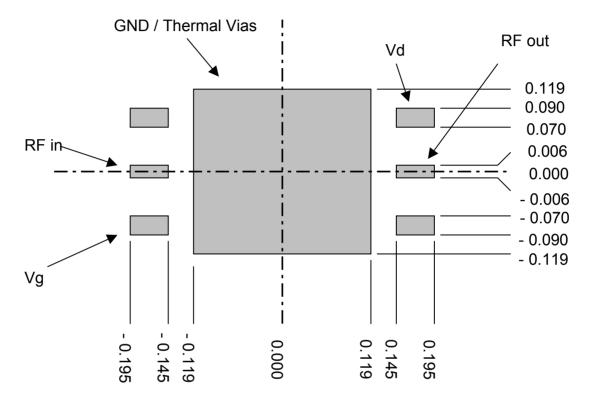
## **Mechanical Drawing**

Note: Devices designated as EPU are typically early in their characterization process prior to finalizing all electrical and process specifications. Specifications are subject to change without notice.

Dimensions in inches Lead planarity is +0.006/-0.002



## **Recommended PWB Land Pattern**



**Dimensions in inches** 

## **Ordering Information**

PART NUMBER	AMPLIFIER APPLICATION
TGA2902-1-SCC-SG	Wideband
TGA2902-2-SCC-SG	VSAT Band

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